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Specification for Approval

Customer:	
Model Name:	

Sı	Customer approval		
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		



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Revision Record

REV NO.	REV DATE	CONTENTS	Note
Α	2019-10-14	NEW ISSUE	

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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

LCM

ITEM	STANDARD VALUES	UNITS
LCD type	2.8"TFT	
Dot arrangement	240(RGB)×320	dots
Color filter array	RGB vertical stripe	
Display mode	Transmission / Normally Black	-
Gray Scale Inversion Direction	80/80/80	
Eyes Viewing Direction	ALL	
Driver IC	ST7789V	
Module size	50.0(W)×69.2(H)×3.7(T)	mm
Active area	43.2(W)×57.6(H)	mm
Dot pitch	0.18(W)×0.18(H)	mm
Interface	i80-system 8/16/18-bitMCU interface 3SPI/4SPI/ 16/18-bitRGB interface	
Operating temperature	-20~ +70	°C
Storage temperature	-30~ +80	°C
Back Light	4 White LED	

RTP

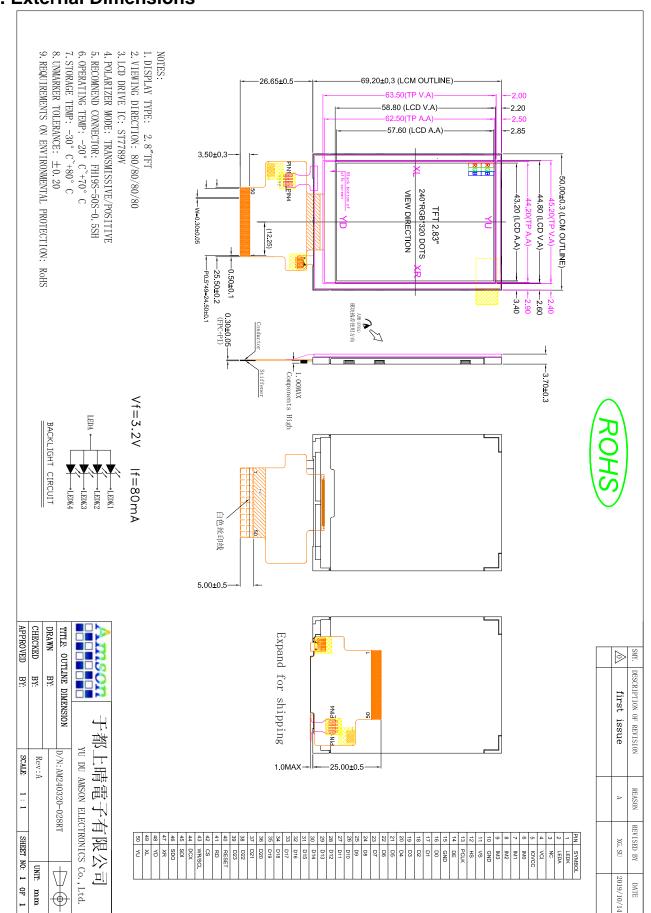
ITEM	STANDARD VALUES	UNITS
RTP type	Film + Glass + FPC	
Surface hardness	3H	
Transmittance	≥78%	
RTP size	49.6(W)×68.8(H)×1.2(T)	mm
Active area	44.20(W)×62.50(H)	mm
Response Time	≤10ms	ms
Linearity	≤1.5%	%
Line writing life	1,000,000	times
Operation force	50~120g	g
Resistance	X:200Ω ~ 550Ω Y:300Ω ~ 900Ω	Ω



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3. External Dimensions





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4. Interface Description

PIN NAME	DESCRIPTION
LEDK	The cathode of LED power
LEDA	The Anode of LED power
NC	NC
VCI	Analog operating voltage.
IOVCC	Logic operating voltage.
IM0~IM3	MPU interface mode select pin,(FYI NOTE1)
GND	Power ground
VSYNC	Frame synchronizing signal for RGB interface operation.
HSYNC	Line synchronizing signal for RGB interface operation.
DOTCLK	Dot clock signal for RGB interface operation.
DE	Data enable signal for RGB interface operation.
GND	Power ground
DB0-DB17	Data bus
DB18~DB23	NC
RESET	Reset pin setting either pin low initializes the LSI Must be reset after power supplied
RD	Read signal input terminal, Active at 'L'.
CS	Chip select signal input terminal, Active at 'L'
/WR	Write enable in MCU parallel interface Display data/command selection pin in 4-line serial interface Second Data lane in 2 data lane serial interfaceIf not used, please fix this pin at VDDI or DGND.
DCX /SCL	Display data/command selection pin in parallel interface. This pin is used to be serial interface clock DCX='1': display data or parameter DCX='0': command data.
SDI	When IM [3]: Low, Serial in/out signal. When IM [3]: High, Serial input signal. The data is applied on the rising edge of the SCL signal.
	Serial output signal.
SDO	The data is applied on the rising edge of the SCL signal.
SDO XR	, ,
	LEDK LEDA NC VCI IOVCC IM0~IM3 GND VSYNC HSYNC DOTCLK DE GND DB0-DB17 DB18~DB23 RESET RD CS /WR DCX /SCL SDI



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49	XL	Touch panel coordinate in the left side of envisage drawing.
50	YU	Touch panel coordinate in the up side of envisage drawing.

Note1:

-The MCU interface mode select.

IM3	IM2	IM1	IM0	MPU Interface Mode	Data pin	
0	0	0	0	80-8bit parallel I/F	DB[7:0]	
0	0	0	1	80-16bit parallel I/F	DB[15:0]	
0	0	1	0	80-9bit parallel I/F	DB[8:0]	
0	0	1	1	80-18bit parallel I/F	DB[17:0],	
	1	•	1	3-line 9bit serial I/F	SDA: in/out	
0	1	0	1	O data lana sarial I/E	SDA: in/out	
				2 data lane serial I/F	WRX: in	
0	1	1	0	4-line 8bit serial I/F	SDA: in/out	
1	0	0	0	0 80-16bit parallel I/F Ⅱ	80-16hit parallel I/E Ⅱ	DB[17:10],
'	O	0	0 60-16bit parallel I/F II		ŭ	DB[8:1]
1	0	0	1	80-8bit parallel I/F Ⅱ	DB[17:10]	
1	0	1	0	80-18bit parallel I/F ∐	DB[17:0],	
1	0	1	1	80-9bit parallel I/F Ⅱ	DB[17:9]	
1	1	0	1	3-line 9bit serial I/F Ⅱ	SDA: in/	
	'	U	'	3-IIIIe anit sellal I/F II	SDO: out	
1	1	1	0	4-line 8bit serial I/F ∏	SDA:in/	
_ '	_	' '	U	4-IIIIe ODIL SEIIAI I/F II	SDO: out	

If not used, please fix this pin at VDDI or DGND.



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5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	٧
Analog Supply Voltage	VCI	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC +0.3	٧
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

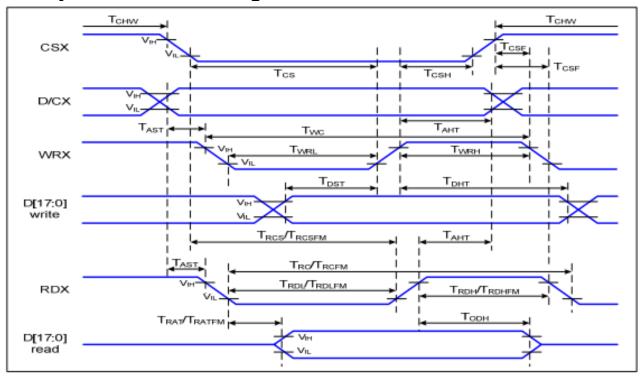
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	2.8	3.3	V	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	V	-
Input High Voltage	V _{IH}	0.7VCI	-	VCI	V	-
Input Low Voltage	V _{IL}	GND	-	0.3 VCI	V	-
Output High Voltage	V _{OH}	0.8 VCI	-	VCI	V	-
Output Low Voltage	V _{OL}	GND	-	0.2 VCI	V	-
I/O Leak Current	lu	-1	-	1	uA	-
Supply Current	IDD	-	7.0	10	mA	-

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7. Timing Characteristics

7.1 i80-System Interface Timing Characteristics



Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX T _{AST}		Address setup time	0		ns	
DICX	T _{AHT}	Address hold time (Write/Read)	10		ns	-
	T _{CHW}	Chip select "H" pulse width	0		ns	
	T _{CS}	Chip select setup time (Write)	15		ns	
CSX	T _{RCS}	Chip select setup time (Read ID)	45		ns	
CSA	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
	T _{WC}	Write cycle	66		ns	
WRX	T _{WRH}	Control pulse "H" duration	15		ns	
	T_{WRL}	Control pulse "L" duration	15		ns	
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T _{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX	T _{RCFM}	Read cycle (FM)	450		ns	When read from
(FM)	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	frame memory
(1 101)	T_{RDLFM}	Control pulse "L" duration (FM)	355		ns	maine memory
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF

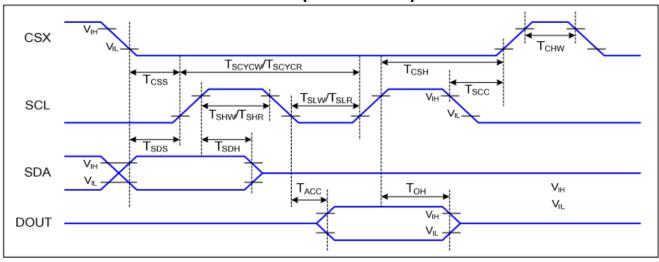


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T _{DH}	нт	Data hold time			ns
T _{RA}	AT	Read access time (ID)		40	ns
T _{RAT}	TFM	Read access time (FM)		340	ns
T _{OD}	DH	Output disable time	20	80	ns

7.2 Serial Interface Characteristics (3-line serial):



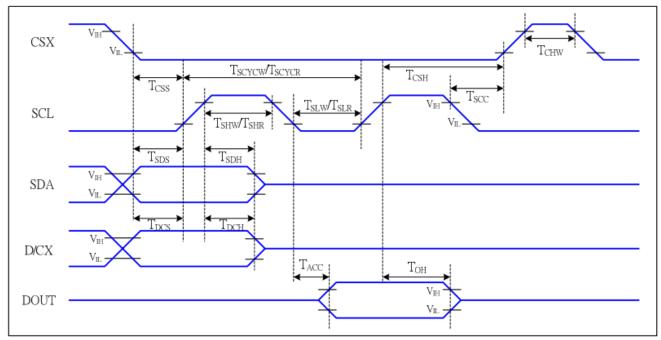
VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 $^\circ$ C

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time			ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
DOUT	T _{OH} Output disable time		15	50	ns	For minimum CL=8pF

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7.3 Serial Interface Characteristics (4-line serial):

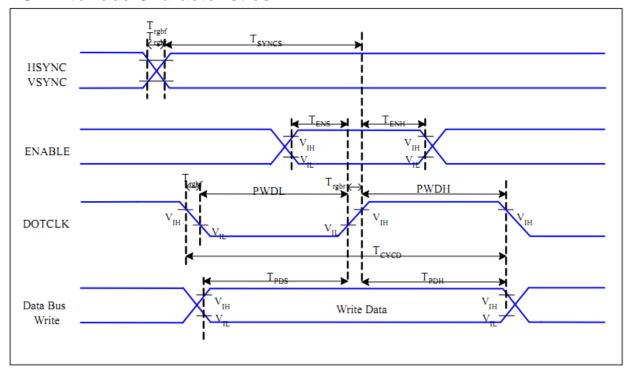


Signal	Symbol	Parameter	MIN	MAX	Unit	Description	
	T _{CSS}	Chip select setup time (write)			ns		
	T _{CSH}	Chip select hold time (write)	15		ns		
CSX	T _{CSS}	Chip select setup time (read)	60		ns		
	T _{SCC}	Chip select hold time (read)	65		ns		
	T _{CHW}	Chip select "H" pulse width	40		ns		
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	urite command ⁹ data	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	-write command & data ram	
SCL T _{SLW}		SCL "L" pulse width (Write)	15		ns	Talli	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	read command 9 data	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	-read command & data ram	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	Idili	
D/CX	T _{DCS}	D/CX setup time	10		ns		
DICX	T _{DCH}	D/CX hold time	10		ns		
SDA	T _{SDS}	Data setup time	10		ns		
(DIN)	T _{SDH}	Data hold time	10		ns		
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF	
D001	T _{OH} Output disable time		15	50	ns	For minimum CL=8pF	

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7.4 RGB Interface Characteristics:



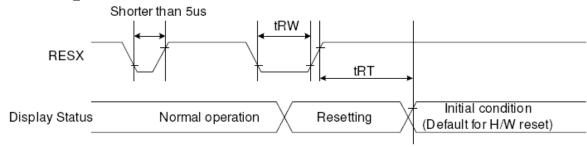
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time		•	ns	
ENABLE	T _{ENS}	Enable Setup Time	25	-	ns	
T _{ENH}		Enable Hold Time		-	ns	
	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
DOTCLK	T _{CYCD}	DOTCLK Cycle Time	120	-	ns	
Trghr, Trghf		DOTCLK Rise/Fall time	-	20	ns	
DB T _{PDS}		PD Data Setup Time	50	-	ns	
DB	T_PDH	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

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7.5 Reset Timing Characteristics



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
	uri I	neset cancel		120 (note 1,6,7)	mS

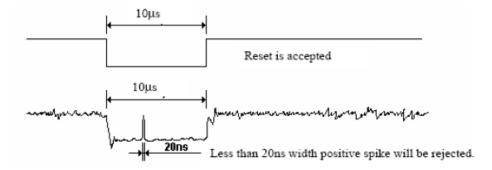
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:

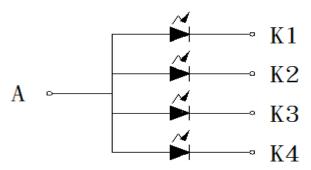


- Note 5: When Reset applied during Sleep In Mode.
- Note 6: When Reset applied during Sleep Out Mode.
- Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

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8. Backlight Characteristic



Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	2.9	3.2	3.5	V	If=80mA
Supply Current	lf	-	80		mA	-
Luminous Intensity for LCM	-	150	180	-	cd/m ²	If=80mA
Uniformity for LCM	-	75	80	-	%	If=80mA
Life Time	-	50000	-	-	Hr	If=80mA
Backlight Color White						



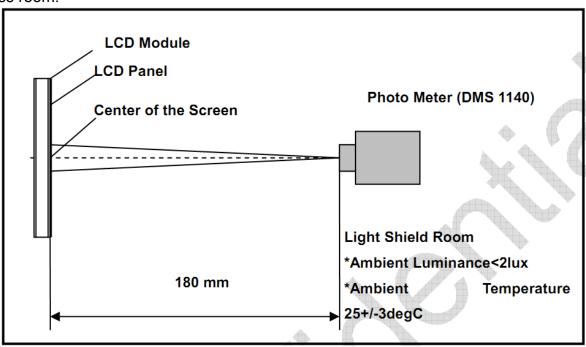
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9. Optical Characteristics

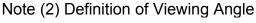
Item	Conditions		Min.	Тур.	Max.	Unit	Note	
	Horizontal	θL	-	80	-			
Viewing Angle	попиона	θR	-	80	-	dograe	(4) (2) (6)	
(CR>10)	Vertical	θт	-	80	-	degree	(1),(2),(6)	
	vertical	θв	-	80	-			
Contrast Ratio	Center		600	800	-	-	(1),(3),(6)	
Response Time	Rising + Fal	ling	-	16	-	ms	(1),(4),(6)	
	Red x			TBD		-		
	Red y			TBD		-	ı	
	Green x			TBD		-		
CF Color	Green y			TBD		-	(1) (6)	
Chromaticity (CIE1931)	Blue x		Typ.	TBD	Typ.	-	(1), (6)	
	Blue y		-0.05	TBD	+0.05	-		
	White x			TBD		-		
	White y			TBD		-		
NTSC	CIE1931		-	60	-	%	(1),(6)	

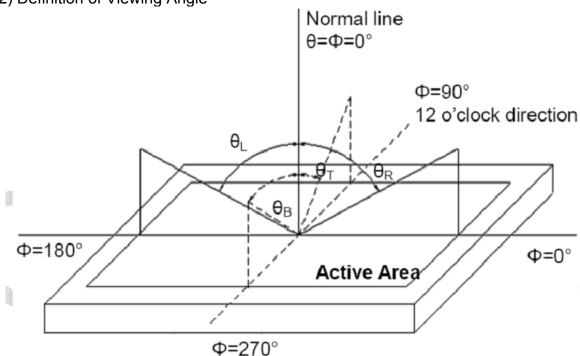
Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.



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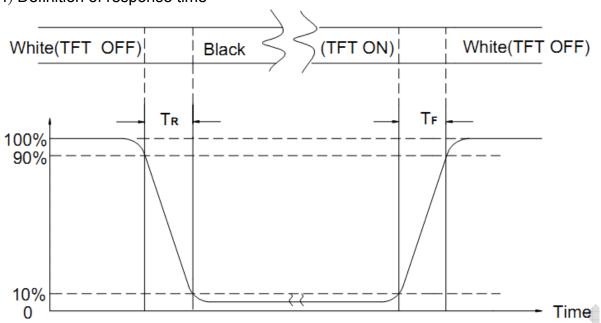


Note (3) Definition of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



Note (5) Definition of Transmittance (Module is without signal input)

Transmittance = Center Luminance of LCD / Center Luminance of Back Light x 100%

Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD



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10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST	
	High Temperature Storage	80°C±2°C×200Hours		
	Low Temperature Storage	-30°C±2°C×200Hours		
	High Temperature Operating	70°C±2°C×120Hours	Inspection after 2~4hours	
	Low Temperature Operating	-20°C±2°C×120Hours	storage at room temperature, the samples should be free from defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments.	
	Temperature Cycle(Storage)	-20°C \longrightarrow 25°C \longrightarrow 70°C (30min) (30min) 1cycle Total 10cycle		
	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	5, Glass crack. 6, Current IDD is twice higher than initial value.	
	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (packing condition test will be tested by a carton)	7, The surface shall be free from damage. 8, The electric characteristic requirements shall be	
	Drooping Test	Drop to the ground from 1M height one time every side of carton. (packing condition test will be tested by a carton)	satisfied.	
	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times		

REMARK:

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test, Pure water(Resistance > 10M Ω)should be used.
- 4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



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11. Inspection Standard

11.1. QUALITY:

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

11.1.1. THE METHOD OF PRESERVING GOODS

AFTER DELIVERY OF GOODS FROM AMSON TO PURCHASER. PURCHASER SHALL CONTROL THE LCM AT -10 °C TO 40 °C ,AND IT MIGHT BE DESIRABLE TO KEEP AT THE NORMAL ROOM TEMPERATURE AND HUMIDITY UNTIL INCOMING INSPECTION OR THROWING INTO PROCESS LINE.

11.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION, A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (SAME AS MIL-STD-105E), LEVEL II SINGLE PLAN.

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %
TOTAL	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION, A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

11.1.3. WARRANTY POLICY

AMSON WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. AMSON WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF AMSON.

11.2. CHECKING CONDITION

- 11.2.1.CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.
- 11.2.2. CHECKER SHALL SEE OVER 300±25 mm. WITH BARE EYES FAR FROM SAMPLE AND USING 2 PCS. OF 20W FLUORESCENT LAMP.



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11.3. INSPECTION PLAN:

TI.3. INSPEC	TION PLAN:	ı	
CLASS	ITEM	JUDGEMENT	CLASS
DA OLUMO A	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO.", "LOT NO." AND "QUANTITY"	Minor
PACKING &		SHOULD INDICATE ON THE PACKAGE.	0.00
INDICATE	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXEDREJECTED	Critical
	3. PRODUCT INDICATION	QUANTITY SHORT OR OVERREJECTED	Maian
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON THE PRODUCT	Major
	4. DIMENSION,	ACCORDING TO SPECIFICATION OR	
ASSEMBLY	LCD GLASS SCRATCH	DRAWING.	Major
ASSEMBLI	AND SCRIBE DEFECT.	DRAWING.	Major
	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE IS VISABLE IN THE VIEWING AREAREJECTED	Minor
	6. BLEMISH - BLACK SPOT -	ACCORDING TO STANDARD OF VISUAL	Minor
	WHITE SPOT IN THE LCD	INSPECTION(INSIDE VIEWING AREA)	Willion
	AND LCD GLASS CRACKS	INGI EGITON(INGIGE VIEWING AREA)	
	7. BLEMISH - BLACK SPOT	ACCORDING TO STANDARD OF VISUAL	Minor
APPEARANCE	WHITE SPOT AND SCRATCH	INSPECTION(INSIDE VIEWING AREA)	
	ON THE POLARIZER		
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL	Minor
		INSPECTION(INSIDE VIEWING AREA)	
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR (OR NEWTON	
		RING) OF LCDREJECTED.	Minor
		OR ACCORDING TO LIMITED SAMPLE	
		(IF NEEDED, AND INSIDE VIEWING AREA)	
	10. ELECTRICAL AND OPTICAL	ACCORDING TO SPECIFICATION OR	Critical
	CHARACTERISTICS	DRAWING . (INSIDE VIEWING AREA)	
	(CONTRAST. VOP.		
	CHROMATICITY ETC)		
ELECTRICAL	11.MISSING LINE	MISSING DOT, LINE, CHARACTER	Critical
		REJECTED	
	12.SHORT CIRCUIT	NO DISPLAY - WRONG PATTERN	Critical
	WRONG PATTERN DISPLAY	DISPLAY · CURRENT CONSUMPTION	
		OUT OF SPECIFICATION REJECTED	
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL	Minor
		INSPECTION	



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11.4	STAN	DARD OF VISUAL INSPECT	TION
NO.	CLASS	ITEM	JUDGEMENT
			(A) ROUND TYPE: unit : mm.
			DIAMETER (mm.) ACCEPTABLE Q'TY
			$\Phi \leq 0.1$ DISREGARD
		BLACK AND WHITE SPOT	$0.1 < \Phi \leq 0.25$ 3 (Distance>5mm)
		FOREIGN MATERIEL	0.25 < Φ 0
11.4.1	MINOR	DUST IN THE CELL	NOTE: Φ =(LENGTH+WIDTH)/2 (B) LINEAR TYPE: unit : mm.
		BLEMISH	LENGTH WIDTH ACCEPTABLE Q'TY
		SCRATCH	W ≤0.03 DISREGARD
			L ≤ 5.0 0.03 < W ≤ 0.07 3 (Distance>5mm)
			0.07 < W FOLLOW ROUND TYPE
			i ozen kosko i i z
			unit : mm.
			DIAMETER ACCEPTABLE Q'TY
		BUBBLE IN POLARIZER	Φ \leq 0.2 DISREGARD
11.4.2	MINOR	DENT ON POLARIZER	$0.2 < \Phi \leq 0.5$ 2 (Distance>5mm)
			0.5 < Φ 0
			Items ACC. Q'TY
		Dot Defect	Bright dot N≤ 4
			Dark dot N≤ 4
11.4.3	MINOR		Pixel Define: Pixel Pixel Pixel Pixel Pixel Pixel Pot Dot Dot Note 1: The definition of dot: The size of a defective dot over 1/2 of whole dot is regarded as one defective dot. Note 2: Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern. Note 3: Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green ,blue pattern.



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NO.	CLASS	ITEM	JUDGEMENT	
11.4.4	MINOR	LCD GLASS CHIPPING	S	Y > S Reject
11.4.5	MINOR	LCD GLASS CHIPPING	SY	X or Y > S Reject
11.4.6	MAJOR	LCD GLASS GLASS CRACK	Y	Y > (1/2) T Reject
11.4.7	MAJOR	LCD GLASS SCRIBE DEFECT	A + B	 a> L/3 , A>1.5mm. Reject B: ACCORDING TO DIMENSION
11.4.8	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL AREA)	T	$\Phi = (x+y)/2 > 2.5 \text{ mm}$ Reject
11.4.9	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL SURFACE)	T Z Y	Y > (1/3) T Reject
11.4.10	MINOR	LCD GLASS CHIPPING	Y Z	Y > T Reject



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12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to POWER or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the maximum operating temperature, 50%Rh or less is required.



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12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT, and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD